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Yan Chen

RESEARCH INTERESTS

Intelligent data and understandable diagnostic and prognostic rules Analysis
Manufacturing process reliability analysis and quality control
Prognostic reconfigurable control

EDUCATION

Present	University of Cincinnati, Cincinnati, Ohio PhD, Candidate
Major	Mechanical Engineering Research Assistant, Center for Intelligent Maintenance System (IMS) Advisor: Professor Jay Lee
03/2006 Degree: Major:	Shanghai Jiao Tong University (SJTU), Shanghai, China M.S. Mechanical Engineering
06/2003: Degree: Major:	Tianjin University (TJU), Tianjin, China B.S. (June 2003) Mechanical & Automation Engineering

RESEARCH/PROJECT EXPERIENCE

- Productivity Improvement through Process Anomaly Detect and Prediction (P&G)
- Embedded prognostic agent in control system (P&G)
- Smart Machine Technology Development and Demonstration Test-Bed (TechSolve Inc.)
- Gear defect analysis based on a new feature selection algorithm.
- Method design and analysis of the convex-damping rig of roller Chain drives in moving walkway systems (the co-operated project by Shanghai Jiao Tong Univ. and Toshiba (China) Co., Ltd).
- Research of the new optimal method for auto-body closure panels fitting with integrating welding thermal effects.

PUBLICATIONS

1. A new method for Feature Selection and gear defect Detection. The conference proceedings of the MSEC2007, SYMP 9 Diagnostics, Performance Prediction and Decision Making for Intelligent Maintenance of Manufacturing Systems.
2. An Automated Modeling Approach of the Planar Mechanisms Analysis. The conference proceedings of the 2005 CIRP Design Seminar, May 22-25, 2005, Shanghai, P.R.China. Ref. CIRP2005-034.
3. New optimal method for auto-body closure panels fitting integrating welding thermal effects, Journal of Automobile Engineering, proceedings of the Institution of Mechanical Engineers Part D (2007, No: 23304, as a co-author).

HONORS AND RANK

- 2006-2008: University Graduate Scholarship, University of Cincinnati
- 2001-2002: Awarded the scholarship for "3A students" (TJU)
- 2000-2001: Awarded the scholarship for "Excellent student leaders" (TJU)
- 1999-2000: Awarded the scholarship for "Excellent student leaders" (TJU)

INTERNSHIP

06/2005 – 09/2005: Diebold Financial Equipment Company Ltd. (china) as an associated engineer in the hardware system department.

03/2006 – 09/2006: Ingersoll Rand Machinery (Shanghai) Co., LTD. Product Engineer Shanghai Engineering COE, PS.

COMPUTER SKILLS

Scientific Programming - Matlab, SAS/JMP, C/C++, JAVA,VB,

Simulation Analysis - Ansys, Adam, UGS, AUTOCAD

Others - Rsllogix, Rsview

LANGUAGES

Chinese - Native

English - Fluent

PERSONAL INTERESTS

Charcoal drawing, sketch and Chinese penmanship, handicraft

Swimming, travelling